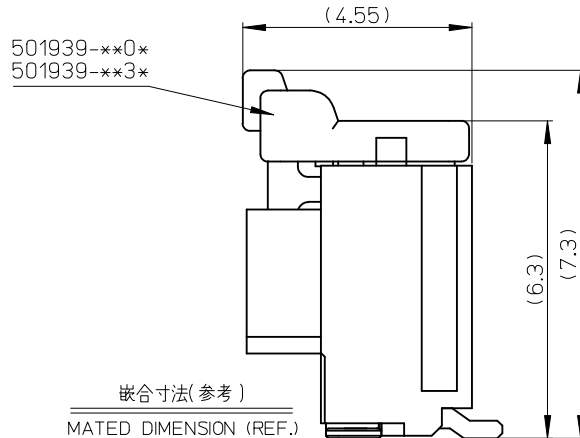
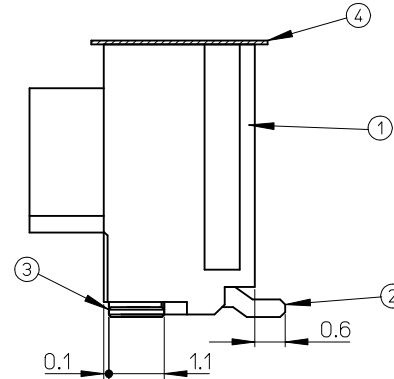
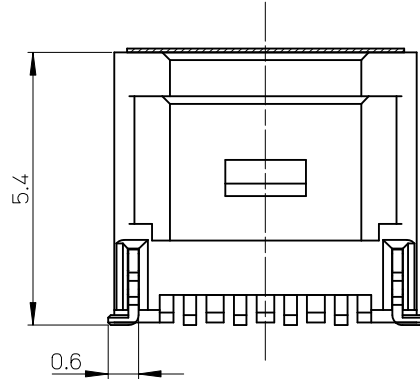
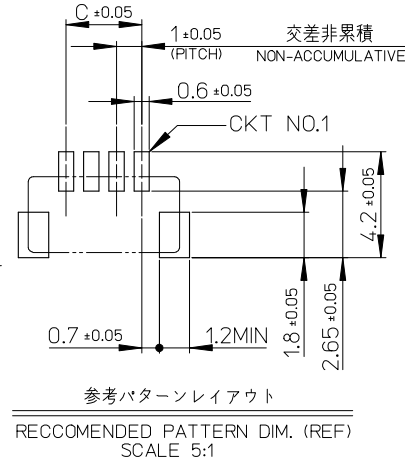
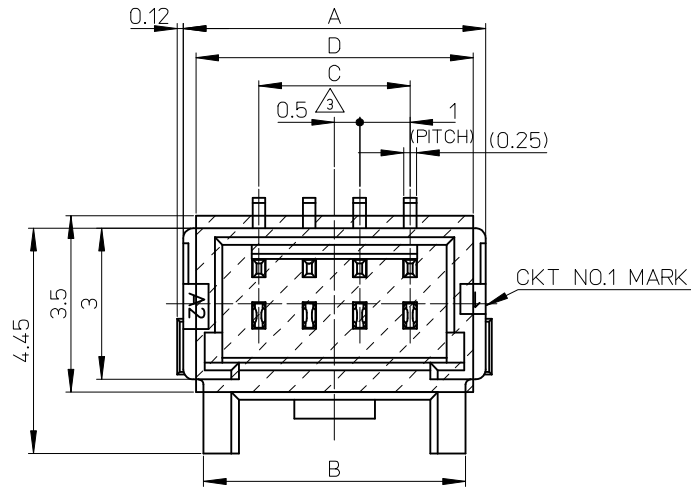




番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON, UL94V-0, COLOR:SEE TABLE
②	溶ダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

- 嵌合相手: 501939-****
MATE WITH: 501939-****
- 溶ダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN

6.5	4.0	5.2	7.0	5
5.5	3.0		6.0	4
4.5	2.0	4.2	5.0	3
D	C	B	A	極数 CIRCUITS

CONNECTOR SERIES No. 501940-****9

REVISED EC NO: J2010-0339 DRWN: TNAKAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW ST POSI-LOCK -LEAD FREE- MOLEX INCORPORATED						
		10 OVER 30 UNDER	±0.25	CHECKED BY AMI ZUMURA	DATE 2005/09/16							
		30 OVER	±0.3	APPROVED BY MYAGI	DATE 2005/09/16							
		ANGULAR ±3 °		MATERIAL NO.							DOCUMENT NO.	SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2							SD-501940-001	
		REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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D

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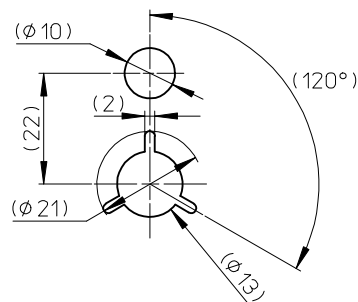
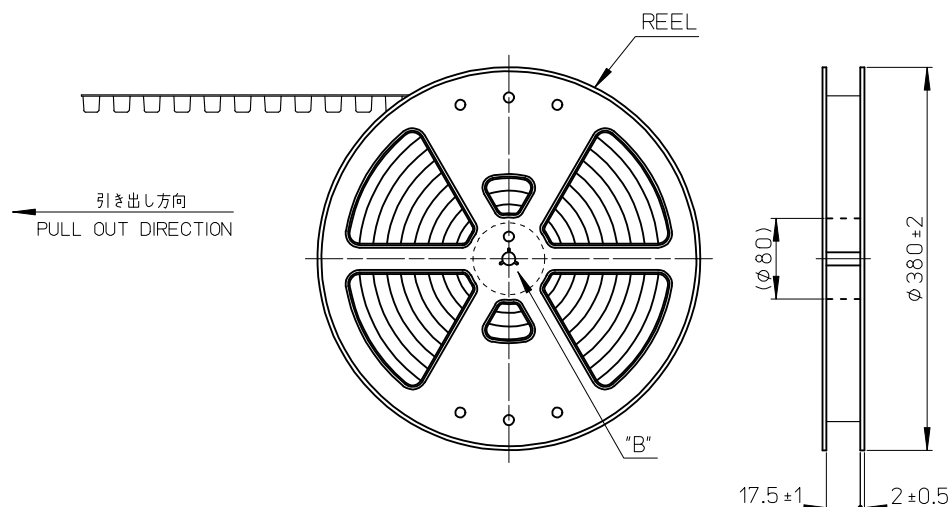
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B

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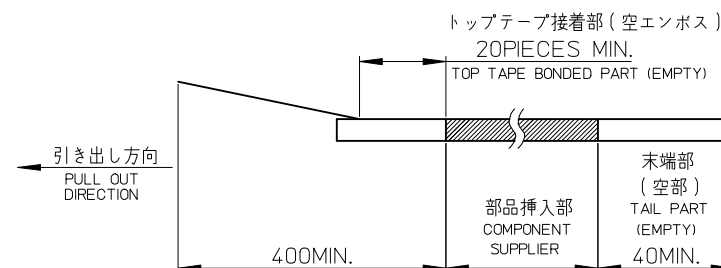
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DETAIL "B"

NOTES

- 製品詳細寸法については製品単体図面を参照ください。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：1100個／リール
NUMBER OF CONNECTORS：1100PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ：ポリスチレン
CARRIER TAPE：POLYSTYRENE
トップテープ：PET、その他
TOP TAPE：PET,OTHER
リール：ポリスチレン<リサイクル材を含む>
REEL：POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
- ハイバリア梱包（シリカゲル入り）対応品である。（501940-**07除く）
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501940-**07)
- 開梱後の保管条件に注意のこと。（ハイバリア品対象：PS-501940-001参照）
REFER TO PS-501940-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2010-0339 DRWN: TNAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW ST EMBSTP PKG -LEAD FREE- MOLEX MOLEX INCORPORATED				
		10 OVER 30 UNDER	± 0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16					
		30 OVER	± 0.3	APPROVED BY MYAGI	DATE 2005/09/16					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501940-002		1 OF 3			
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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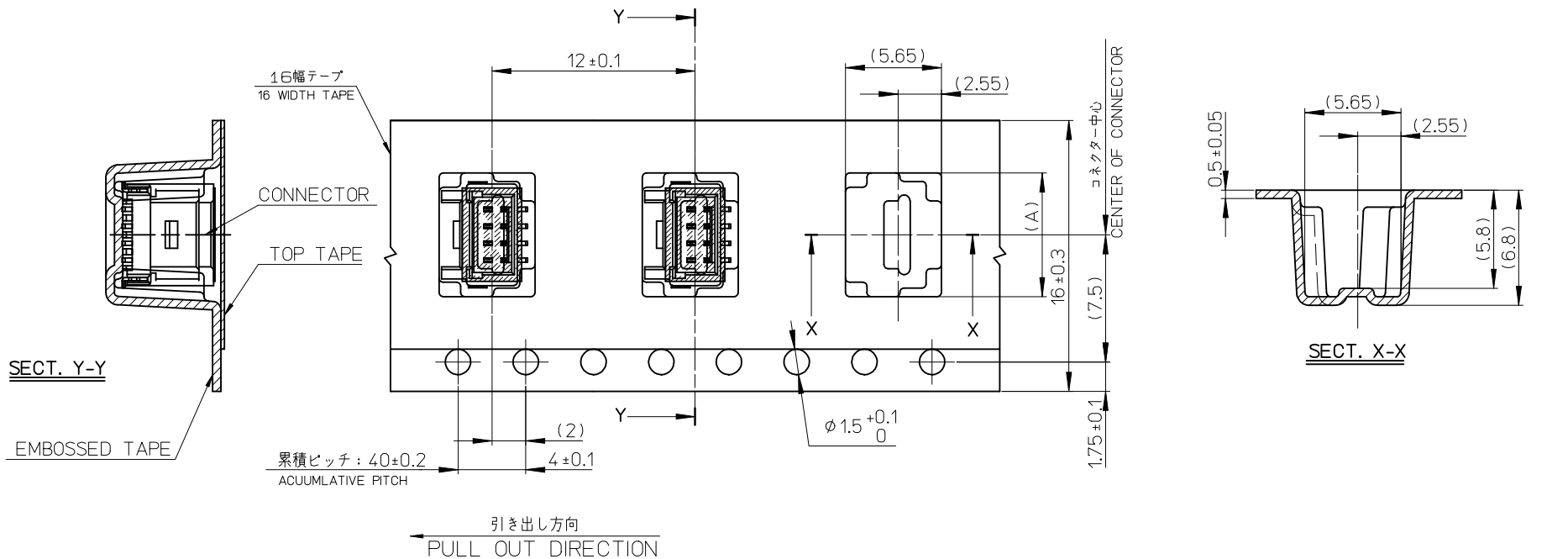
E

D

C

B

A



8.3	5
7.3	4
6.3	3
(A)	極数 CIRCUITS

REVISED EC NO: J2010-0339 DRWN: TNAKAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2005/09/16	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW ST EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY AMIZUMURA	DATE 2005/09/16					
		30 OVER	± 0.3	APPROVED BY MYAGI	DATE 2005/09/16	 MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501940-002		2 OF 3			
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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[illegible]